

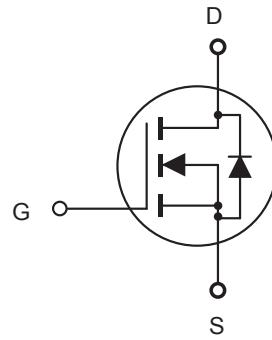
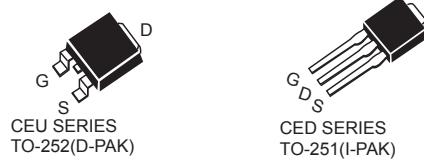


CED3060/CEU3060

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 30V, 75A , $R_{DS(ON)} = 6.6\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
 $R_{DS(ON)} = 9.5\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



ABSOLUTE MAXIMUM RATINGS

 $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	75	A
Drain Current-Pulsed ^a	I_{DM}	300	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	62.5 0.5	W W/ $^\circ\text{C}$
Operating and Store Temperature Range	T_J, T_{Stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.0	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ\text{C/W}$

Details are subject to change without notice .

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CED3060/CEU3060

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^c						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	1		3	V
Static Drain-Source	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 30\text{A}$		5.5	6.6	$\text{m}\Omega$
On-Resistance		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 30\text{A}$		7.5	9.5	$\text{m}\Omega$
Dynamic Characteristics^d						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2465		pF
Output Capacitance	C_{oss}			330		pF
Reverse Transfer Capacitance	C_{rss}			190		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_{\text{D}} = 1\text{A}, \square$ $V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		18	36	ns
Turn-On Rise Time	t_r			5	10	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			51	102	ns
Turn-Off Fall Time	t_f			10	20	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 16\text{A}, \square$ $V_{\text{GS}} = 5\text{V}$		15.6	20.3	nC
Gate-Source Charge	Q_{gs}			5.2		nC
Gate-Drain Charge	Q_{gd}			3.2		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				75	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$			1.3	V

Notes : □

a.Repetitive Rating : Pulse width limited by maximum junction temperature.□

b.Surface Mounted on FR4 Board, $t \leq 10 \text{ sec.}$ □

c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.□

d.Guaranteed by design, not subject to production testing.□

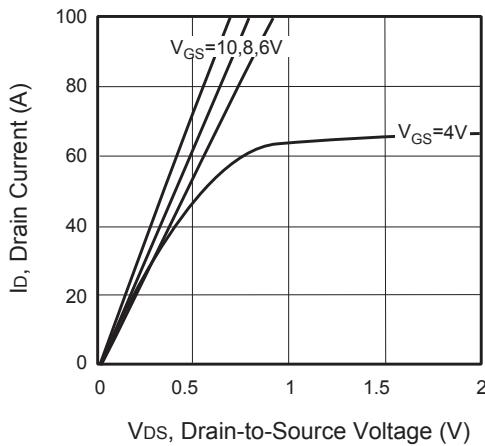


Figure 1. Output Characteristics

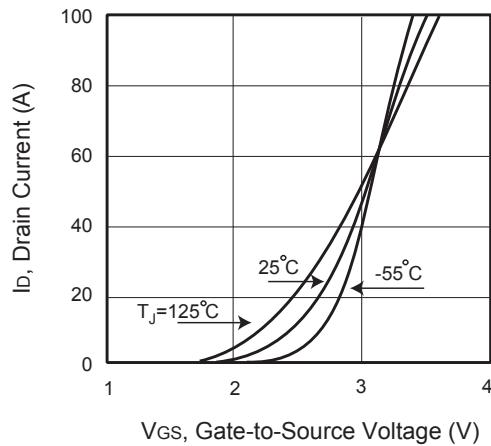


Figure 2. Transfer Characteristics

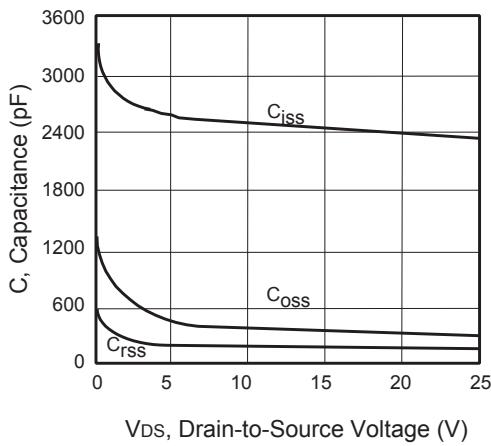


Figure 3. Capacitance

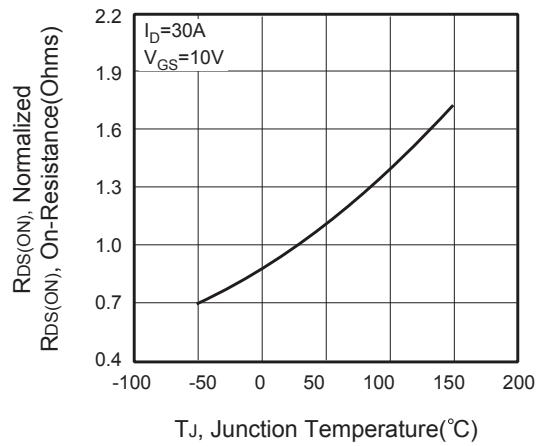


Figure 4. On-Resistance Variation with Temperature

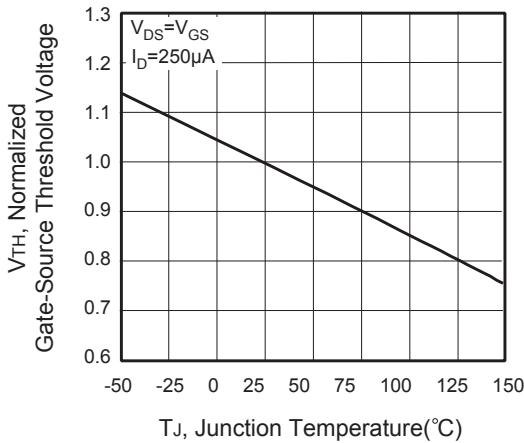


Figure 5. Gate Threshold Variation with Temperature

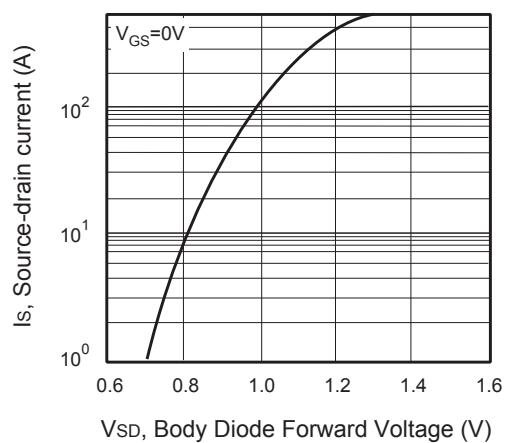


Figure 6. Body Diode Forward Voltage Variation with Source Current

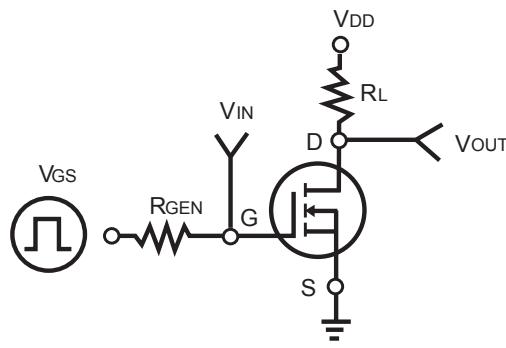
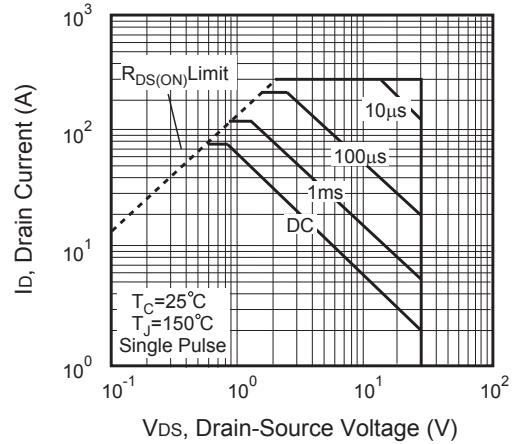
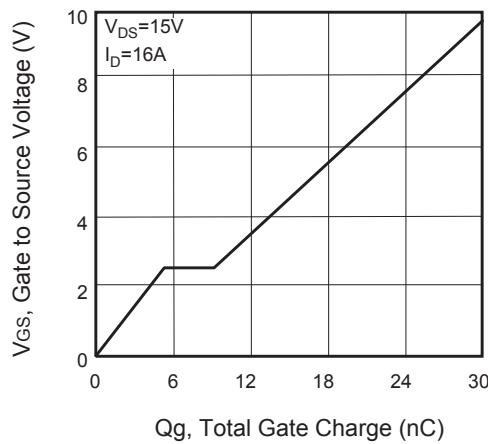


Figure 9. Switching Test Circuit

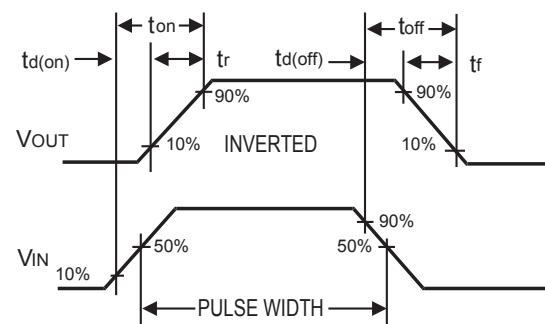


Figure 10. Switching Waveforms

